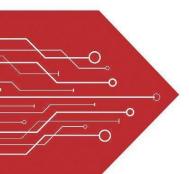
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet

www.msksemi.com

Features

Ultra low leakage: nA level

Operating voltage: 5V

Low clamping voltage

• Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±15kV Contact discharge: ±8kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

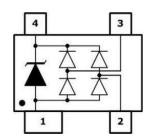
- IEC61000-4-5 (Lightning) 3A (8/20μs)

RoHS Compliant

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

Pin Configuration



SOT-143

Electrical Characteristics (TA=25°C unless otherwise specified)

	VRWM	V _{BR} I _T V _C	Vc	Vc		I _R	С	
P/N	(V) (V)		(mA)	@1A	(Max)	(@A)	μA (Max)	(Pf) (Typ.)
PSR05-MS	5	6	1	9.8	23	3	1	1.2

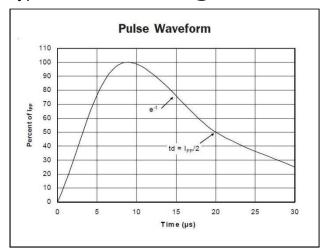
Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

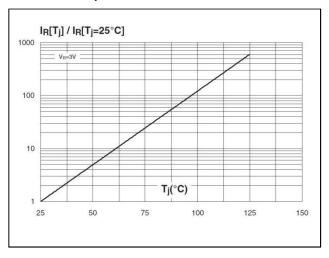
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ррр	300	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	±15	Kv
ESD per IEC 61000-4-2 (Contact)	V ESD	±8	rxv
Operating Temperature Range	TJ	-55 to +125	$^{\circ}$
Storage Temperature Range	T _{STJ}	-55 to +150	${\mathbb C}$

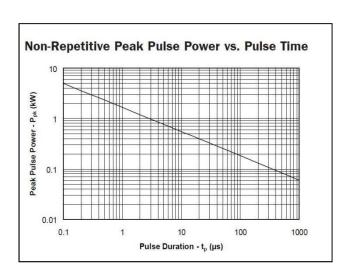


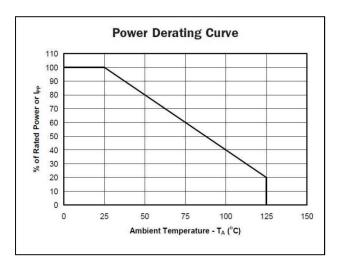


Typical Characteristics@ Ta=25°C unless otherwise specified



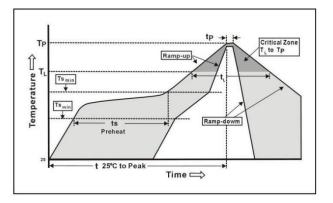


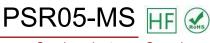




Soldering Parameters

Reflow Condition		Fb – Free assembly		
	-Temperature Min (T _{s(Min)})	150°C		
Pre Heat	- Temperature Max (T _{s(Max)})	200°C		
	-Time (Min to max) (t _s)	60 - 180 secs		
Average r	amp up rate (Liquidus) Temp k	3°C/second Max		
T _{S (Max)} to T _L - Ramp-up Rate		3°C/second Max		
	-Temperature (T _L) (Liquidus)	217°C		
Reflow	-Temperature (t _L)	60 - 150 seconds		
Peak Tem	perature (T _p)	250+0/-5 °C		
Time within 5°C of actual peak Temperature (t,)		20 – 40 seconds		
Ramp-dov	vm Rate	6°C/second Max		
Time 25°C	to peak Temperature (T _p)	8 minutes Max.		
Do not ex	ceed	260°C		

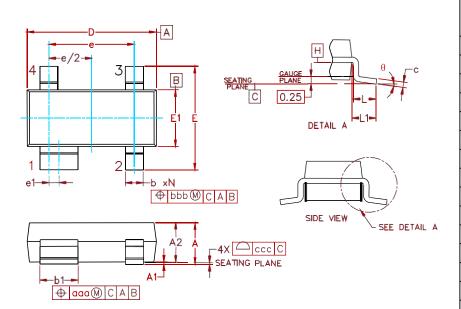






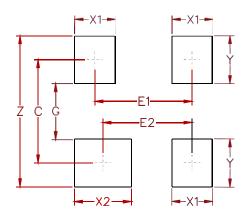


PACKAGE MECHANICAL DATA



Symbol		Inches		Millimeters			
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.	
Α	0.031	-	0.048	0.80	-	1.22	
A 1	0.000	-	0.008	0.013	-	0.15	
A2	0.020	0.035	0.042	0.75	0.90	1.07	
b	0.011	-	0.020	0.30	1	0.51	
b1	0.029	-	0.037	0.76	-	0.94	
C	0.003	1	0.008	0.08	1	0.20	
D	0.110	0.114	0.120	2.80	2.90	3.04	
Е	0.082	0.093	0.104	2.10	2.37	2.64	
E1	0.047	0.051	0.055	1.20	1.30	1.40	
е		0.075		1.92 BSC			
e1	0.008			0.20 BSC			
L	0.015	0.020	0.024	0.40	0.50	0.60	
L1		(0.021)		(0.54)			
N		4		4			
θ	0°	-	8°	0°	-	8°	
aaa		0.006		0.15			
bbb		0.008		0.20			
ccc		0.004		0.10			

Suggested Pad Layout



REEL SPECIFICATION

P/N	PKG	QTY
PSR05-MS	SOT-143	3000



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